

11 Electrical Data

The following sections describe recommended electrical connections for the Am5_X86 microprocessors and electrical specifications.

11.1 Power and Grounding

11.1.1 Power Connections

Am5 $_{\rm X}$ 86 microprocessors with 16 Kbytes of cache have modest power requirements. However, the high clock frequency output buffers can cause power surges as multiple output buffers drive new signal levels simultaneously. For clean, on-chip power distribution at high frequency, 23 $V_{\rm CC}$ pins and 28 $V_{\rm SS}$ pins feed the microprocessor in the 168-pin PGA package. The 208-pin SQFP package includes 53 $V_{\rm CC}$ pins and 38 $V_{\rm SS}$ pins.

Power and ground connections must be made to all external $V_{\rm CC}$ and $V_{\rm SS}$ pins of the microprocessors. On a circuit board, all $V_{\rm CC}$ pins must connect to a $V_{\rm CC}$ plane. Likewise, all $V_{\rm SS}$ pins must connect to a common GND plane.

The ${\rm Am5}_{\chi}86$ microprocessor family requires only 3.3 V as input power. Unlike other 3-V processors, the ${\rm Am5}_{\chi}86$ microprocessor family does not require a V_{CC5} input of 5 V to indicate the presence of 5-V I/O devices on the system motherboard. For socket compatibility, this pin is INC, allowing the ${\rm Am5}_{\chi}86$ CPU to operate in 3-V sockets in systems that use 5-V I/O.

11.1.2 Power Decoupling Recommendations

Liberal decoupling capacitance should be placed near the microprocessor. The microprocessor, driving its 32bit parallel address and data buses at high frequencies, can cause transient power surges, particularly when driving large capacitive loads.

Low inductance capacitors and interconnects are recommended for best high-frequency electrical performance. Inductance can be reduced by shortening circuit board traces between the microprocessor and the decoupling capacitors. Capacitors designed specifically for use with PGA packages are commercially available.

11.1.3 Other Connection Recommendations

For reliable operation, always connect unused inputs to an appropriate signal level. Active Low inputs should be connected to $V_{\rm CC}$ through a pull-up resistor. Pull-ups in the range of 20 K Ω are recommended. Active High inputs should be connected to GND.



ABSOLUTE MAXIMUM RATINGS

Case Temperature under Bias $...-65^{\circ}\text{C}$ to +110°C Storage Temperature $...-65^{\circ}\text{C}$ to +150°C Voltage on any pin with respect to ground ...-0.5 V to V_{cc} +2.6 V Supply voltage with respect to V_{SS} ...-0.5 V to +4.6 V

Stresses above those listed under Absolute Maximum Ratings may cause permanent device failure. Functionality at or above these limits is not implied. Exposure to Absolute Maximum Ratings for extended periods may affect device reliability.

OPERATING RANGES

Commercial (C) Devices

T_{CASE} 0°C to 85°C V_{CC} 3.3 V ±0.3 V

Operating Ranges define those limits between which the functionality of the device is guaranteed.

DC CHARACTERISTICS over COMMERCIAL operating ranges

 $V_{CC} = 3.3 \text{ V} \pm 0.3 \text{ V}; T_{CASE} = 0^{\circ}\text{C to} + 85^{\circ}\text{C}$

		Prelim	inary Info			
Symbol	Parameter	Min	Max	Notes		
V _{IL}	Input Low Voltage	– 0.3 V	+0.8 V			
V _{IH}	Input High Voltage	2.0 V	V _{CC} + 2.4 V			
V _{OL}	Output Low Voltage		0.45 V	Note 1		
V _{OH}	Output High Voltage	2.4 V		Note 2		
lcc	Power Supply Current: 133 MHz		931 mA	Typical supply current: 825 mA @ 133 MHz. Inputs at rails, outputs unloaded.		
ICCSTOPGRANT or ICCAUTOHALT	Input Current in Stop Grant or Auto Halt mode 133 MHz		93 mA	Typical supply current for Stop Grant or Auto Halt mode: 50 mA @ 133 MHz.		
ССЅТРСЬК	Input Current in Stop Clock mode		5 mA	Typical supply current in Stop Clock mode is 600 μA.		
ILI	Input Leakage Current		±15 µA	Note 3		
1 _{IH}	Input Leakage Current		200 μΑ	Note 4		
I _{IL}	Input Leakage Current		– 400 µA	Note 5		
lo	Output Leakage Current		±15 μΑ			
CIN	Input Capacitance		10 pF	F _C = 1 MHz (Note 6)		
Co	I/O or Output Capacitance		14 pF	F _C = 1 MHz (Note 6)		
C _{CLK}	CLK Capacitance		12 pF	F _C = 1 MHz (Note 6)		

Notes:

- 1. This parameter is measured at: Address, Data, $\overline{BE3} \overline{BE0} = 4.0 \text{ mA}$; Definition, Control = 5.0 mA
- 2. This parameter is measured at: Address, Data, BE3-BE0 = -1.0 mA; Definition, Control = -0.9 mA
- 3. This parameter is for inputs without internal pull-ups or pull-downs and $0 \le V_{tN} \le V_{CC}$.
- 4. This parameter is for inputs with internal pull-downs and $V_{\rm HI} = 2.4 \ \rm V.$
- 5. This parameter is for inputs with internal pull-ups and $V_{II} = 0.45 \text{ V}$.
- 6. Not 100% tested.



SWITCHING CHARACTERISTICS over COMMERCIAL operating ranges

The AC specifications, provided in the AC characteristics table, consist of output delays, input setup requirements, and input hold requirements. All AC specifications are relative to the rising edge of the CLK signal. AC specifications measurement is defined by Figure 39. All timings are referenced to 1.5 V unless otherwise specified. Am5x86 microprocessor output delays are

specified with minimum and maximum limits, measured as shown. The minimum microprocessor delay times are hold times provided to external circuitry. Input setup and hold times are specified as minimums, defining the smallest acceptable sampling window. Within the sampling window, a synchronous input signal must be stable for correct microprocessor operation.

33-MHz bus (133-MHz operating frequency)

 $V_{CC} = 3.3 \text{ V} \pm 0.3 \text{ V}$; $T_{CASE} = 0^{\circ}\text{C}$ to + 85°C; $C_L = 50 \text{ pF}$ unless otherwise specified

Symbol	Parameter	Preliminary Info				
		Min	Max	Unit	Figure	Notes
	Frequency	8	33	MHz		Note 2
t ₁	CLK Period	30	125	ns	39	
t _{1a}	CLK Period Stability		0.1%	Δ		Adjacent Clocks Notes 3 and 4
t ₂	CLK High Time at 2 V	11		ns	39	Note 3
t_3	CLK Low Time at 0.8 V	11		ns	39	Note 3
t ₄	CLK Fall Time (2 V-0.8 V)		3	ns	39	Note 3
t ₅	CLK Rise Time (0.8 V-2 V)		3	ns	39	Note 3
t ₆	A31-A2, PWT, PCD, BE3-BE0, M/IO, D/C, CACHE, W/R, ADS, LOCK, FERR, BREQ, HLDA, SMIACT, HITM Valid Delay	3	14	ns	40	Note 5
t ₇	A31-A2, PWT, PCD, BE3-BE0, M/IO, D/C, CACHE, W/R, ADS, LOCK Float Delay	3	20	ns	41	Note 3
t ₈	PCHK Valid Delay	3	14	ns	42	
t _{8a}	BLAST, PLOCK, Valid Delay	3	14	ns	40	
t ₉	BLAST, PLOCK, Float Delay	3	20	ns	41	Note 3
t ₁₀	D31-D0, DP3-DP0 Write Data Valid Delay	3	14	ns	40	
t ₁₁	D31-D0, DP3-DP0 Write Data Float Delay	3	20	ns	41	Note 3
t ₁₂	EADS, INV, WB/WT Setup Time	5		ns	43	
t ₁₃	EADS, INV, WB/WT Hold Time	3		ns	43	
t ₁₄	KEN, BS16, BS8 Setup Time	5		ns	43	Control of
t ₁₅	KEN, BS16, BS8 Hold Time	3		ns	43	
t ₁₆	RDY, BRDY Setup Time	5		ns	44	
t ₁₇	RDY, BRDY Hold Time	3		ns	44	
t ₁₈	HOLD, AHOLD Setup Time	6		ns	4 3	
t _{18a}	BOFF Setup Time	7		ns	43	
t ₁₉	HOLD, AHOLD, BOFF Hold Time	3		ns	43	
t ₂₀	RESET, FLUSH, A20M, NMI, INTR, IGNNE, STPCLK, SRESET, SMI Setup Time	5		ns	43	Note 5
t ₂₁	RESET, FLUSH, A20M, NMI, INTR, IGNNE, STPCLK, SRESET, SMI Hold Time	3		ns	43	Note 5
t ₂₂	D31-D0, DP3-DP0, A31-A4 Read Setup Time	5		ns	43, 44	
t ₂₃	D32-D0, DP3-DP0, A31-A4 Read Hold Time	3		ns	43, 44	

- Specifications assume $C_L = 50$ pF. I/O Buffer model must be used to determine delays due to loading (trace and component). First Order I/O buffer models for the processor are available.
- 2. 0-MHz operation guaranteed during stop clock operation.
- 3. Not 100% tested. Guaranteed by design characterization.
- 4. For faster transitions (>0.1% between adjacent clocks), use the Stop Clock protocol to switch operating frequency.
- 5. All timings are referenced at 1.5 V (as illustrated in the listed figures) unless otherwise noted.



${\rm Am5_X86~Microprocessor~AC~Characteristics~for}$ Boundary Scan Test Signals at 25 MHz

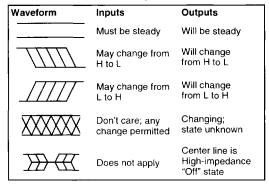
 V_{CC} = 3.3 V ±0.3 V; T_{CASE} = 0°C to +85°C; C_L = 50 pF unless otherwise specified

		Preliminary Info				
Symbol	Parameter	Min	Max	Unit	Figure	Notes
t ₂₄	TCK Frequency		25	MHz		1x Clock
t ₂₅	TCK Period	40		ns	45, 46	Note 1
t ₂₆	TCK High Time at 2 V	10		ns	45	
t ₂₇	TCK Low Time at 0.8 V	10		ns	45	
t ₂₈	TCK Rise Time (0.8 V-2 V)		4	ns	45	Note 2
t ₂₉	TCK Fall Time (2 V-0.8 V)		4	ns	45	Note 2
t ₃₀	TDI, TMS Setup Time	8		ns	46	Note 3
t ₃₁	TDI, TMS Hold Time	7		ns	46	Note 3
t ₃₂	TDO Valid Delay	3	25	ns	46	Note 3
t ₃₃	TDO Float Delay		36	ns	46	Note 3
t ₃₄	All Outputs (Non-Test) Valid Delay	3	25	ns	46	Note 3
t ₃₅	All Outputs (Non-Test) Float Delay		30	ns	46	Note 3
t ₃₆	All Inputs (Non-Test) Setup Delay	8		ns	46	Note 3
t ₃₇	All Inputs (Non-Test) Hold Time	7		ns	46	Note 3

Notes:

- 1. TCK period ≥ CLK period.
- 2. Rise/Fall times can be relaxed by 1 ns per 10-ns increase in TCK period.
- 3. Parameter measured from TCK.

Key to Switching Waveforms



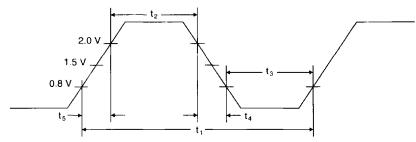


Figure 39. CLK Waveforms

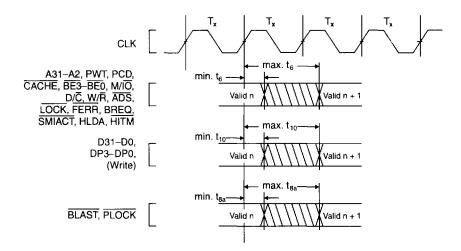


Figure 40. Output Valid Delay Timing

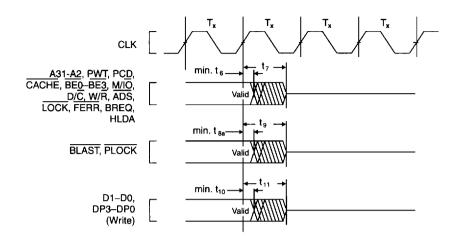


Figure 41. Maximum Float Delay Timing

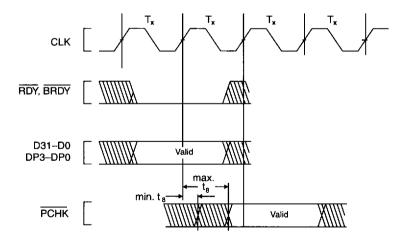


Figure 42. PCHK Valid Delay Timing

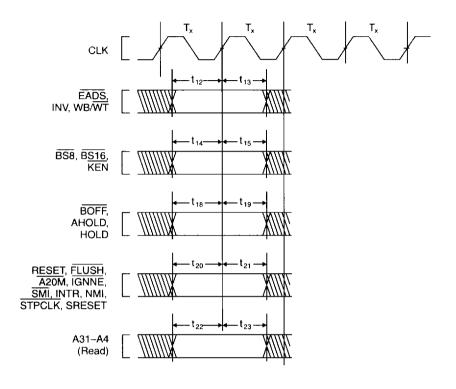


Figure 43. Input Setup and Hold Timing

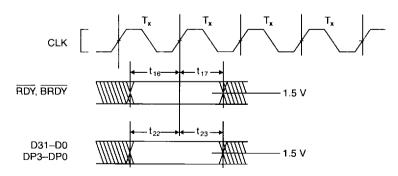


Figure 44. RDY and BRDY Input Setup and Hold Timing

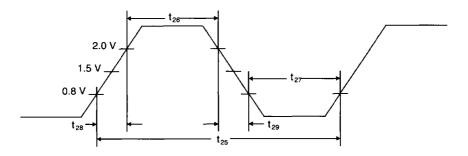


Figure 45. TCK Waveforms

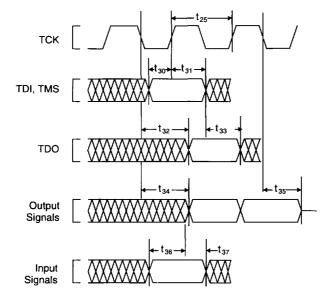


Figure 46. Test Signal Timing Diagram